# KAQV27x Series 5PIN N.O TYPE

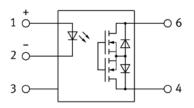
SOLID STATE RELAY- SIC MOSFET OUTPUT

#### Description

The KAQV27x series is a SPST normally open switch (1 Form A) that is ideally suited for controlling low-level signals and various types of loads.

It is constructed using a GaAlAs LED for actuation control and an integrated monolithic die for the switch output. The die, fabricated in a high-voltage dielectrically isolated technology, is comprised of a photodiode array, switch control circuitry and SiC-MOSFET.

#### Schematic



#### Features

- 1. Silicon carbide SiC MOSFET Output
- 2. High load voltage with low on-resistance
- 3. Fast reverse recovery time
- 4. Isolation voltage between input and output Viso: 5,000 Vrms
- 5. 5-pin DIP and SMD package

### Application

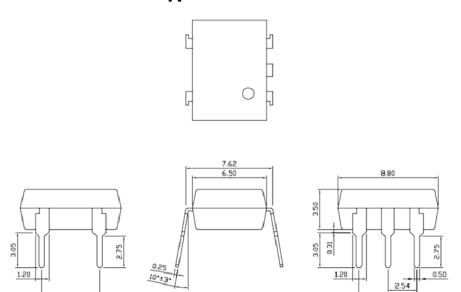
- Industrial Automation
- Battery Management
- Building Automation
- EV Charger
- Measurement Equipment

Unit: mm

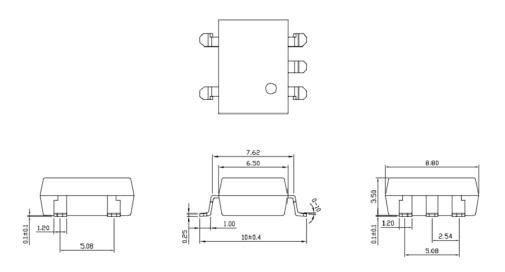


Outside Dimension

# 1.Dual-in-line type.

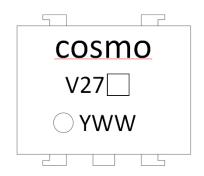


# 2.Surface mount type.



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# Device Marking



Notes:

cosmo

V27 ☐ Part No. V271 \ V272

YWW Y: Year code / W: Week code

# Absolute Maximum Ratings

(Ta=25°C)

	Parameter	□ymbol		R⊡ting	Unit
Input	Continuous forward current	I <sub>F</sub>	50		mA
	Peak forward current	I <sub>FP</sub>	1		А
	Reverse volt⊑ge	$V_R$	5		V
	Power dissipat □o □	P <sub>in</sub>	75		mW
Output	Load voltage(Peak AC or DC)	V <sub>L</sub>	V271	1500	M
			V272	1800	V
	Continuous load current	IL	V271	50	A
			V272	30	mA
	Peak load current	I <sub>peak</sub>	80		mA
	Power dissipation	P <sub>out</sub>	450		mW
Isolation voltage		V <sub>iso</sub>	5000		Vrms
Total power dissipation		$P_t$	500		mW
Derate linearly from 25°C		-	2.5		mW/°C
Operating temperature □		$T_{opr}$	-40 to +110		°C
Storage temperature		$T_{stg}$	-40 to +125		°C
Junction temperature		Tj	125		°C
Soldering temperature 10 seconds		T <sub>sot</sub>	260		°C

# **KAQV27x Series**

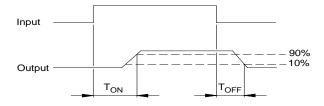
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# • Electro-optical Characteristics

(Ta=25°ℂ)

	Parameter	Symbol	Conditions	Min.	Тур.	Max.	Uni t
Input	Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$		1.2	1.5	V
	Operation input current	I <sub>FON</sub>	I <sub>L</sub> = Max.		1.0	3.0	mA
	Recovery input current	I <sub>FOFF</sub>	I <sub>L</sub> = Max.	0.2	-	1.3	mA
Output	On resistance	R <sub>on</sub>	$I_F = 10 \text{ mA}$ , $I_L = 50 \text{mA}$ . Within 1 s	-	25	100	Ω
	Off-state leakage current	I <sub>LEAK</sub>	I <sub>F</sub> = 0 mA ,V <sub>L</sub> = 1500V	-	-	1	
			I <sub>F</sub> = 0 mA ,V <sub>L</sub> = 1800V		10		μA
I/O capacitance		C <sub>iso</sub>	f = 1 MHz, V <sub>B</sub> = 0 V	-	1.3	3	pF
Initial I/O isolation resistance		R <sub>iso</sub>	500 V DC	1,000	-	-	МΩ
Turn-on time		T <sub>ON</sub>	I 10m A I Mov	-	0.1	0.5	ms
Turn-off time		T <sub>OFF</sub>	$I_F=10$ mA, $I_L=$ Max.	-	0.4	1.0	ms

## Turn-on / Turn-off Time





# **KAQV27x Series**

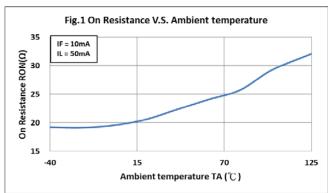
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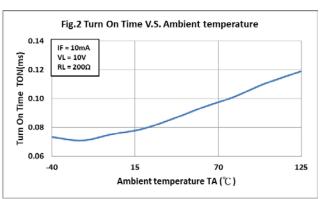
Schematic and Wiring Diagrams

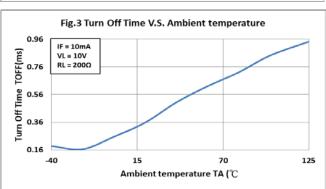
Schematic	Output Configuration	Load	Connection	Wiring Diagrams
1 0 0 6 2 0 4	1a	AC DC	-	E T I V (AC, DC)

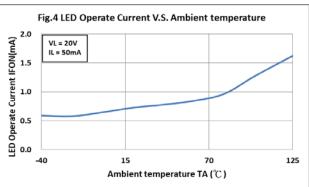


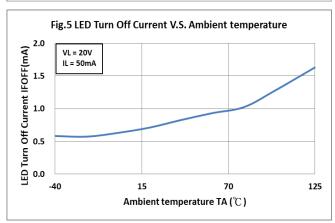
### • TYPICAL PERFORMANCE CURVES & TEST CIRCUITS

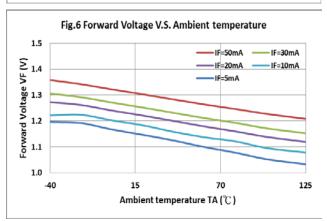


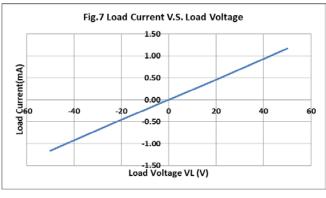


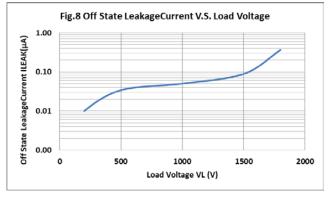






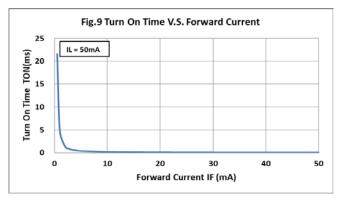


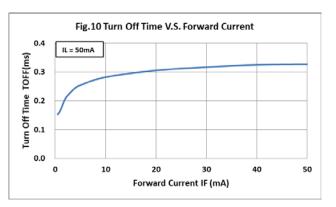




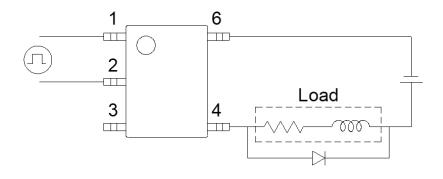
# KAQV27x Series 5PIN N.O TYPE

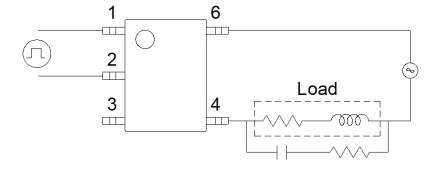
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# Using Methods





R-C Snubber



# KAQV27x Series 5PIN N.O TYPE SOLID STATE RELAY- SIC MOSFET OUTPUT

### Recommended Soldering Conditions

#### (a) Infrared reflow soldering:

■ Peak reflow soldering : 260°C or below (package surface temperature)

■ Time of peak reflow temperature: 10 sec
 ■ Time of temperature higher than 230°C: 30-60 sec
 ■ Time to preheat temperature from 60-120 sec

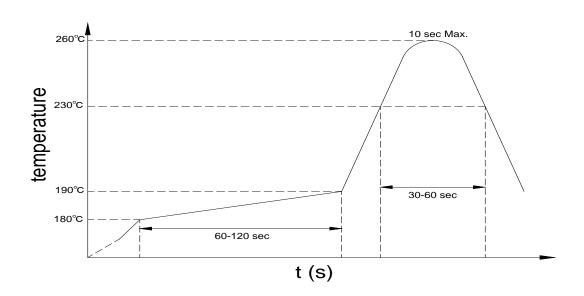
180~190°C ∶ Two

■ Number of reflows : Rosin flux containing small amount of chlorine (The

■ Flux : flux with a maximum chlorine content of 0.2 Wt% is

recommended.)

### **Recommended Temperature Profile of Infrared Reflow**



#### (b) Wave soldering:

■ Temperature : 260°C or below (molten solder temperature)

■ Time : 10 seconds or less

■ Preheating conditions: 120°C or below (package surface temperature)

■ Number of times : One

■ Flux : Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(c) Cautions:

■ Fluxes: Avoid removing the residual flux with freon-based and

chlorine-based cleaning solvent.

Avoid shorting between portion of frame and leads.



# Numbering System

# **KAQV271** X (Y)

#### Notes:

KAQV271 = Part No.

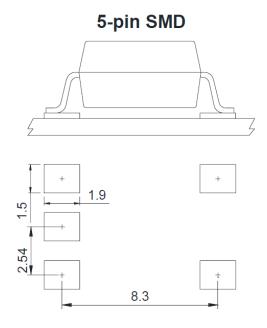
X = Lead form option (blank or A)

Y = Tape and reel option (  $TL \cdot TR$  )

Option	Description	Packing quantity	
A (TL)	surface mount type package + TL tape & reel option	1000 units per reel	
A (TR)	surfa⊡e mount type package + TR tape & reel option	1000 units pe⊡reel	

# Recommended Pad Layout for Surface Mount Lead Form

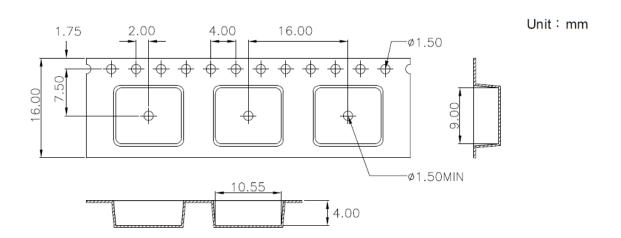
# 1. Surface mount type.



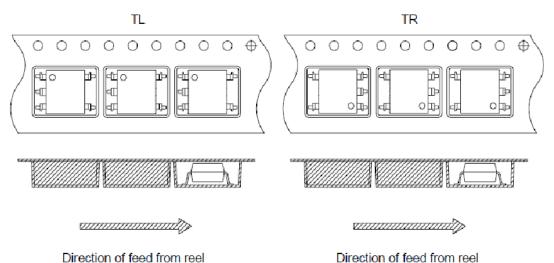
Unit: mm



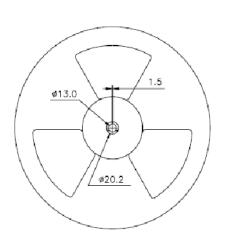
### • 6-pin SMD Carrier Tape & Reel

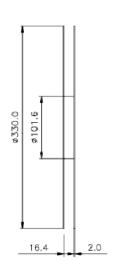


TOLERANCE: ±0.2mm



Direction of feed from reel







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